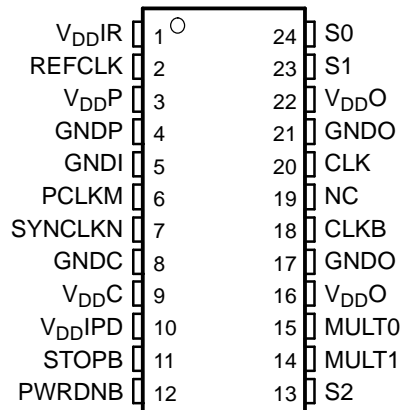


## DIRECT RAMBUS™ CLOCK GENERATOR

### FEATURES

- 533-MHz Differential Clock Source for Direct Rambus™ Memory Systems for an 1066-MHz Data Transfer Rate
- Fail-Safe Power Up Initialization
- Synchronizes the Clock Domains of the Rambus Channel With an External System or Processor Clock
- Three Power Operating Modes to Minimize Power for Mobile and Other Power-Sensitive Applications
- Operates From a Single 3.3-V Supply and 120 mW at 300 MHz (Typ)
- Packaged in a Shrink Small-Outline Package (DBQ)
- Supports Frequency Multipliers: 4, 6, 8, 16/3
- No External Components Required for PLL
- Supports Independent Channel Clocking
- Spread Spectrum Clocking Tracking Capability to Reduce EMI
- Designed for Use With TI's 133-MHz Clock Synthesizers CDC924 and CDC921
- Cycle-Cycle Jitter Is Less Than 40 ps at 533 MHz
- Certified by Gigatest Labs to Exceed the Rambus DRCG Validation Requirement
- Supports Industrial Temperature Range of –40°C to 85°C

**DBQ PACKAGE  
(TOP VIEW)**



NC – No internal connection

### DESCRIPTION

The Direct Rambus clock generator (DRCG) provides the necessary clock signals to support a Direct Rambus memory subsystem. It includes signals to synchronize the Direct Rambus channel clock to an external system or processor clock. It is designed to support Direct Rambus memory on a desktop, workstation, server, and mobile PC motherboards. DRCG also provides an off-the-shelf solution for a broad range of Direct Rambus memory applications.

The DRCG provides clock multiplication and phase alignment for a Direct Rambus memory subsystem to enable synchronous communication between the Rambus channel and ASIC clock domains. In a Direct Rambus memory subsystem, a system clock source provides the REFCLK and PCLK clock references to the DRCG and memory controller, respectively. The DRCG multiplies REFCLK and drives a high-speed BUSCLK to RDRAMs and the memory controller. Gear ratio logic in the memory controller divides the PCLK and BUSCLK frequencies by ratios M and N such that PCLKM = SYNCLKN, where SYNCLK = BUSCLK/4. The DRCG detects the phase difference between PCLKM and SYNCLKN and adjusts the phase of BUSCLK such that the skew between PCLKM and SYNCLKN is minimized. This allows data to be transferred across the SYNCLK/PCLK boundary without incurring additional latency.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

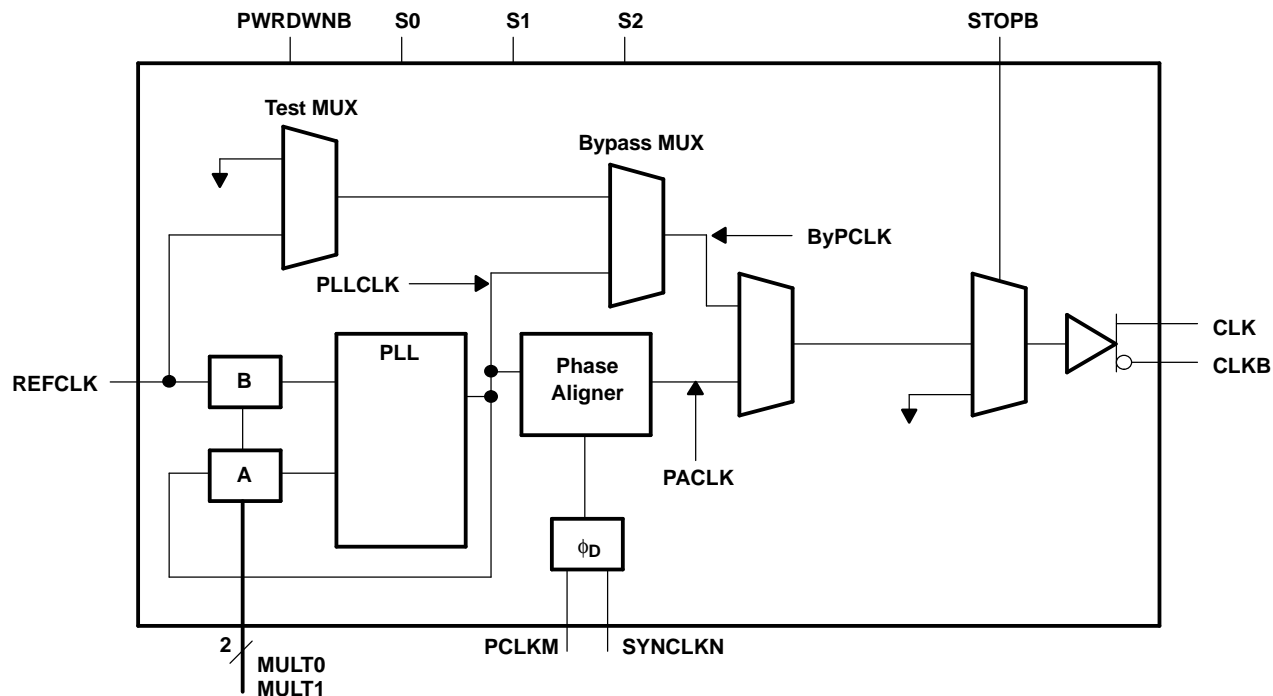
DIRECT RAMBUS, Rambus are trademarks of Rambus Inc.

User control is provided by multiply and mode selection terminals. The multiply terminals provide selection of one of four clock frequency multiply ratios, generating BUSCLK frequencies ranging from 267 MHz to 533 MHz with clock references ranging from 33 MHz to 100 MHz. The mode select terminals can be used to select a bypass mode where the frequency multiplied reference clock is directly output to the Rambus channel for systems where synchronization between the Rambus clock and a system clock is not required. Test modes are provided to bypass the PLL and output REFCLK on the Rambus channel and to place the outputs in a high-impedance state for board testing.

The CDCFR83A has a fail-safe power up initialization state-machine which supports proper operation under all power up conditions.

The CDCFR83A is characterized for operation over free-air temperatures of –40°C to 85°C.

**FUNCTIONAL BLOCK DIAGRAM**



**FUNCTION TABLE<sup>(1)</sup>**

MODE	S0	S1	S2	CLK	CLKB
Normal	0	0	0	Phase aligned clock	Phase aligned clock B
Bypass	1	0	0	PLLCLK	PLLCLKB
Test	1	1	0	REFCLK	REFCLKB
Output test (OE)	0	1	x	Hi-Z	Hi-Z
Reserved	0	0	1	–	–
Reserved	1	0	1	–	–
Reserved	1	1	1	Hi-Z	Hi-Z

(1) X = don't care, Hi-Z = high impedance

**TERMINAL FUNCTIONS**

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
CLK	20	O	Output clock
CLKB	18	O	Output clock (complement)
GNDC	8		GND for phase aligner
GNDI	5		GND for control inputs
GNDO	17, 21		GND for clock outputs
GNDP	4		GND for PLL
MULT0	15	I	PLL multiplier select
MULT1	14	I	PLL multiplier select
NC	19		Not used
PCLKM	6	I	Phase detector input
PWRDNB	12	I	Active low power down
REFCLK	2	I	Reference clock
S0	24	I	Mode control
S1	23	I	Mode control
S2	13	I	Mode control
STOPB	11	I	Active low output disable
SYNCLKN	7	I	Phase detector input
V <sub>DD</sub> C	9		V <sub>DD</sub> for phase aligner
V <sub>DD</sub> IPD	10		Reference voltage for phase detector inputs and STOPB
V <sub>DD</sub> IR	1		Reference voltage for REFCLK
V <sub>DD</sub> O	16, 22		V <sub>DD</sub> for clock outputs
V <sub>DD</sub> P	3		V <sub>DD</sub> for PLL

## PLL DIVIDER SELECTION

Table 1 lists the supported REFCLK and BUSCLK frequencies. Other REFCLK frequencies are permitted, provided that (267 MHz < BUSCLK < 533 MHz) and (33 MHz < REFCLK < 100 MHz).

**Table 1. REFCLK and BUSCLK Frequencies**

MULT0	MULT1	REFCLK (MHz)	MULTIPLY RATIO	BUSCLK <sup>(1)</sup> (MHz)
0	0	67	4	267
0	1	50	6	300
0	1	67	6	400
1	1	33	8	267
1	1	50	8	400
1	1	67	8	533
1	0	67	16/3	356

- (1) BUSCLK will be undefined until a valid reference clock is available at REFCLK. After applying REFCLK, the PLL requires stabilization time to achieve phase lock.

**Table 2. Clock Output Driver States**

STATE	PWRDNB	STOPB	CLK	CLKB
Powerdown	0	X	GND	GND
CLK stop	1	0	V <sub>X</sub> , STOP	V <sub>X</sub> , STOP
Normal	1	1	PACLK/PLLCLK/REFCLK <sup>(1)</sup>	PACLB/PLLCLKB/REFCLKB

- (1) Depending on the state of S0, S1, and S2

## ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	UNIT
V <sub>DD</sub> Supply voltage range <sup>(2)</sup>	–0.5 V to 4 V
V <sub>O</sub> Output voltage range at any output terminal	–0.5 V to V <sub>DD</sub> + 0.5 V
V <sub>I</sub> Input voltage range at any input terminal	–0.5 V to V <sub>DD</sub> + 0.5 V
Continuous total power dissipation	See Dissipation Rating Table
T <sub>A</sub> Operating free-air temperature range	–40°C to 85°C
T <sub>stg</sub> Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.  
 (2) All voltage values are with respect to the GND terminals.

## DISSIPATION RATINGS

PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C <sup>(1)</sup>	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
DBQ	1400 mW	11 mW/°C	905 mW	740 mW

- (1) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

## RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
$V_{DD}$	Supply voltage	3.135	3.3	3.465	V
$V_{IH}$	High-level input voltage (CMOS)	$0.7 \times V_{DD}$			V
$V_{IL}$	Low-level input voltage (CMOS)			$0.3 \times V_{DD}$	V
	Initial phase error at phase detector inputs (required range for phase aligner)	$-0.5 \times t_{c(PD)}$		$0.5 \times t_{c(PD)}$	V
$V_{IL}$	REFCLK low-level input voltage			$0.3 \times V_{DDIR}$	V
$V_{IH}$	REFCLK high-level input voltage	$0.7 \times V_{DDIR}$			V
$V_{IL}$	Input signal low voltage (STOPB)			$0.3 \times V_{DDIPD}$	V
$V_{IH}$	Input signal high voltage (STOPB)	$0.7 \times V_{DDIPD}$			V
	Input reference voltage for (REFCLK) ( $V_{DDIR}$ )	1.235		3.465	V
	Input reference voltage for (PCLKM and SYSCLKN) ( $V_{DDIPD}$ )	1.235		3.465	V
$I_{OH}$	High-level output current			-16	mA
$I_{OL}$	Low-level output current			16	mA
$T_A$	Operating free-air temperature	-40		85	°C

## TIMING REQUIREMENTS

		MIN	MAX	UNIT
$t_{c(in)}$	Input cycle time	10	40	ns
	Input cycle-to-cycle jitter		250	ps
	Input duty cycle over 10,000 cycles	40%	60%	
$f_{mod}$	Input frequency modulation	30	33	kHz
	Modulation index, nonlinear maximum 0.5%		0.6%	
	Phase detector input cycle time (PCLKM and SYNCLKN)	30	100	ns
SR	Input slew rate	1	4	V/ns
	Input duty cycle (PCLKM and SYNCLKN)	25%	75%	

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS <sup>(1)</sup>	MIN	TYP <sup>(2)</sup>	MAX	UNIT		
V <sub>O(STOP)</sub>	Output voltage during CLK Stop (STOPB = 0)		See Figure 1	1.1		2			
V <sub>O(X)</sub>	Output crossing-point voltage		See Figure 1 and Figure 6	1.3		1.8	V		
V <sub>O</sub>	Output voltage swing		See Figure 1	0.4		0.6	V		
V <sub>IK</sub>	Input clamp voltage		V <sub>DD</sub> = 3.135 V, I <sub>I</sub> = –18 mA			–1.2	V		
V <sub>OH</sub>	High-level output voltage		See Figure 1			2	V		
			V <sub>DD</sub> = min to max, I <sub>OH</sub> = –1 mA	V <sub>DD</sub> – 0.1					
			V <sub>DD</sub> = 3.135 V, I <sub>OH</sub> = –16 mA	2.4					
V <sub>OL</sub>	Low-level output voltage		See Figure 1	1			V		
			V <sub>DD</sub> = min to max, I <sub>OH</sub> = 1 mA			0.1			
			V <sub>DD</sub> = 3.135 V, I <sub>OH</sub> = 16 mA			0.5			
I <sub>OH</sub>	High-level output current		V <sub>DD</sub> = 3.135 V, V <sub>O</sub> = 1 V	–32	–52		mA		
			V <sub>DD</sub> = 3.3 V, V <sub>O</sub> = 1.65 V		–51				
			V <sub>DD</sub> = 3.465 V, V <sub>O</sub> = 3.135 V		–14.5	–21			
I <sub>OL</sub>	Low-level output current		V <sub>DD</sub> = 3.135 V, V <sub>O</sub> = 1.95 V	43	61.5		mA		
			V <sub>DD</sub> = 3.3 V, V <sub>O</sub> = 1.65 V		65				
			V <sub>DD</sub> = 3.465 V, V <sub>O</sub> = 0.4 V		25.5	36			
I <sub>OZ</sub>	High-impedance-state output current		S0 = 0, S1 = 1			±10	μA		
I <sub>OZ(STOP)</sub>	High-impedance-state output current during CLK stop		Stop = 0, V <sub>O</sub> = GND or V <sub>DD</sub>			±100	μA		
I <sub>OZ(PD)</sub>	High-impedance-state output current in power-down state		PWRDNB = 0, V <sub>O</sub> = GND or V <sub>DD</sub>	–10		100	μA		
I <sub>IH</sub>	High-level input current	REFCLK, PCLKM, SYNCCLKN, STOPB	V <sub>DD</sub> = 3.465 V, V <sub>I</sub> = V <sub>DD</sub>			10	μA		
		PWRDNB, S0, S1, S2, MULT0, MULT1				10			
I <sub>IL</sub>	Low-level input current	REFCLK, PCLKM, SYNCCLKN, STOPB	V <sub>DD</sub> = 3.465 V, V <sub>I</sub> = 0			–10	μA		
		PWRDNB, S0, S1, S2, MULT0, MULT1				–10			
Z <sub>O</sub>	Output impedance	High state	R <sub>I</sub> at I <sub>O</sub> – 14.5 mA to –16.5 mA			15	35	50	Ω
		Low state	R <sub>I</sub> at I <sub>O</sub> 14.5 mA to 16.5 mA			11	17	35	
	Reference current	V <sub>DD</sub> IR, V <sub>DD</sub> IPD	V <sub>DD</sub> = 3.465 V	PWRDNB = 0			50	μA	
				PWRDNB = 1			0.5	mA	
C <sub>I</sub>	Input capacitance		V <sub>I</sub> = V <sub>DD</sub> or GND			2		pF	
C <sub>O</sub>	Output capacitance		V <sub>O</sub> = V <sub>DD</sub> or GND			3		pF	
I <sub>DD(PD)</sub>	Supply current in pwoer-down state		REFCLK = 0 MHz to 100 MHz, PWDNB = 0, STOPB = 1				100	μA	
I <sub>DD(CLKSTOP)</sub>	Supply current in CLK stop state		BUSCLK configured for 533 MHz				45	mA	
I <sub>DD(NORMAL)</sub>	Supply current in normal state		BUSCLK = 533 MHz				100	mA	

(1) V<sub>DD</sub> refers to any of the following; V<sub>DD</sub>, V<sub>DD</sub>IPD, V<sub>DD</sub>IR, V<sub>DD</sub>O, V<sub>DD</sub>C, and V<sub>DD</sub>P

(2) All typical values are at V<sub>DD</sub> = 3.3 V, T<sub>A</sub> = 25°C.

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$t_{c(out)}$	Clock output cycle time			1.87		3.75	ns
$t_{(jitter)}$	Total cycle jitter over 1, 2, 3, 4, 5, or 6 clock cycles	267 MHz	See Figure 3			80	ps
		300 MHz				70	
		356 MHz				60	
		400 MHz				50	
		533 MHz <sup>(2)</sup>				40	
$t_{(phase)}$	Phase detector phase error for distributed loop		Static phase error <sup>(3)</sup>	–100		100	ps
$t_{(phase, SSC)}$	PLL output phase error when tracking SSC		Dynamic phase error <sup>(3)</sup>	–100		100	ps
$I_{(DC)}$	Output duty cycle over 10,000 cycles		See Figure 4	45%		55%	
$t_{(DC, err)}$	Output cycle-to-cycle duty cycle error	267 MHz	See Figure 5			80	ps
		300 MHz				70	
		356 MHz				60	
		400 MHz				50	
		533 MHz				50	
$t_r, t_f$	Output rise and fall times (measured at 20%–80% of output voltage)		See Figure 7	160		400	ps
$\Delta t$	Difference between rise and fall times on a single device (20%–80%) $ t_r - t_f $		See Figure 7			100	ps

(1) All typical values are at  $V_{DD} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

(2) Jitter measurement according to Rambus validation specification

(3) Assured by design

## STATE TRANSITION LATENCY SPECIFICATIONS

PARAMETER		FROM	TO	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$t_{(powerup)}$	Delay time, PWRDNB $\uparrow$ to CLK/CLKB output settled (excluding $t_{(DISTLOCK)}$ )	Powerdown	Normal	See Figure 8			3	ms
	Delay time, PWRDNB $\uparrow$ to internal PLL and clock are on and settled						3	
$t_{(VDDpowerup)}$	Delay time, power up to CLK/CLKB output settled	$V_{DD}$	Normal	See Figure 8			3	ms
	Delay time, power up to internal PLL and clock are on and settled						3	
$t_{(MULT)}$	MULT0 and MULT1 change to CLK/CLKB output resettled (excluding $t_{(DISTLOCK)}$ )	Normal	Normal	See Figure 9			1	ms
$t_{(CLKON)}$	STOPB $\uparrow$ to CLK/CLKB glitch-free clock edges	CLK Stop	Normal	See Figure 10			10	ns
$t_{(CLKSETL)}$	STOPB $\uparrow$ to CLK/CLKB output settled to within 50 ps of the phase before STOPB was disabled	CLK Stop	Normal	See Figure 10			20	cycles
$t_{(CLKOFF)}$	STOPB $\downarrow$ to CLK/CLKB output disabled	Normal	CLK Stop	See Figure 10			5	ns
$t_{(powerdown)}$	Delay time, PWRDNB $\downarrow$ to the device in the power-down mode	Normal	Powerdown	See Figure 8			1	ms
$t_{(STOP)}$	Maximum time in CLKSTOP (STOPB = 0) before reentering normal mode (STOPB = 1)	STOPB	Normal	See Figure 10			100	$\mu\text{s}$
$t_{(ON)}$	Minimum time in normal mode (STOPB = 1) before reentering CLKSTOP (STOPB = 0)	Normal	CLK Stop	See Figure 10	100			ms
$t_{(DISTLOCK)}$	Time from when CLK/CLKB output is settled to when the phase error between SYNCLKN and PCLKM falls within $t_{(phase)}$	Unlocked	Locked				5	ms

(1) All typical values are at  $V_{DD} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

### PARAMETER MEASUREMENT INFORMATION

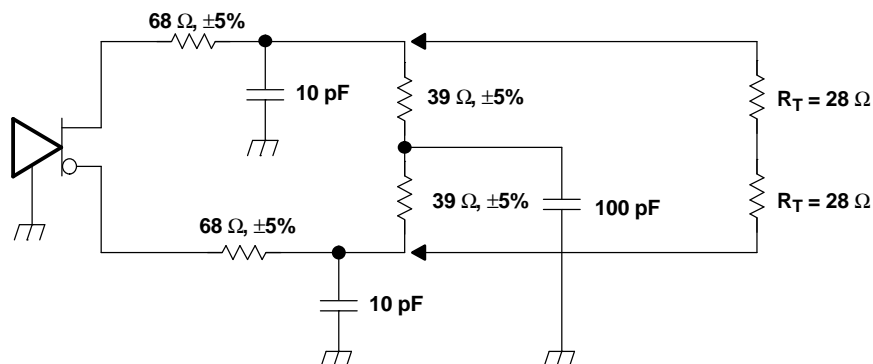
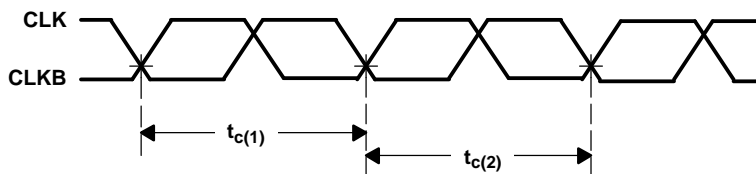
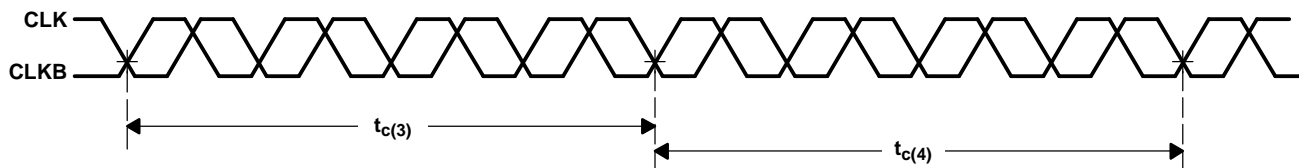


Figure 1. Test Load and Voltage Definitions ( $V_{O(STOP)}$ ,  $V_{O(X)}$ ,  $V_O$ ,  $V_{OH}$ ,  $V_{OL}$ )



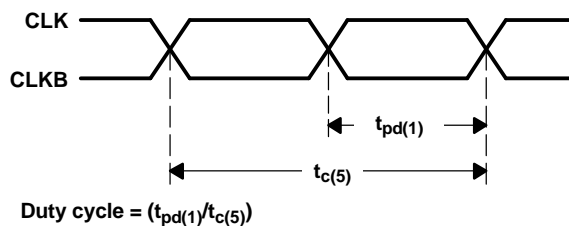
$$\text{Cycle-to-cycle jitter} = |t_{c(1)} - t_{c(2)}| \text{ over 10000 consecutive cycles}$$

Figure 2. Cycle-to-Cycle Jitter



$$\text{Cycle-to-cycle jitter} = |t_{c(3)} - t_{c(4)}| \text{ over 10000 consecutive cycles}$$

Figure 3. Short Term Cycle-to-Cycle Jitter Over Four Cycles



$$\text{Duty cycle} = (t_{pd(1)} / t_{c(5)})$$

Figure 4. Output Duty Cycle



## PARAMETER MEASUREMENT INFORMATION (continued)

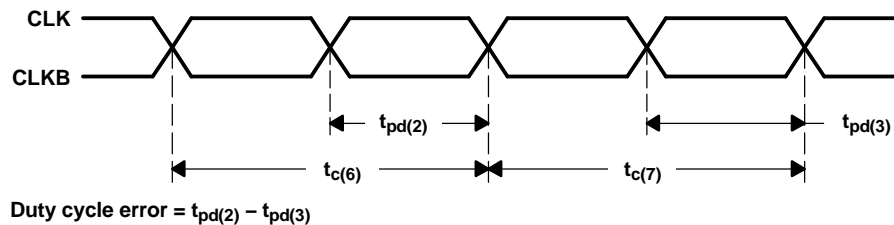


Figure 5. Duty Cycle Error (Cycle-to-Cycle)

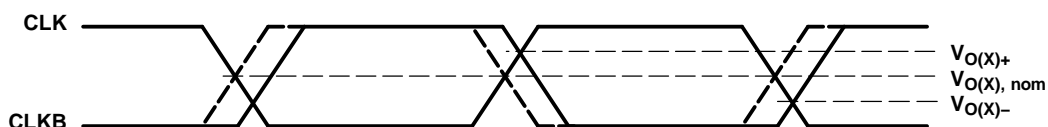


Figure 6. Crossing-Point Voltage



Figure 7. Voltage Waveforms

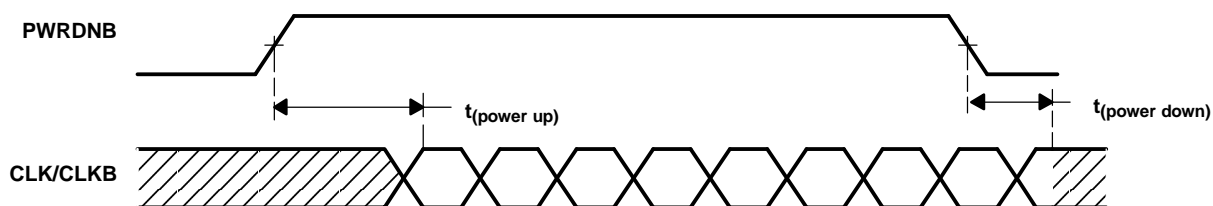


Figure 8. PWRDNB Transition Timings

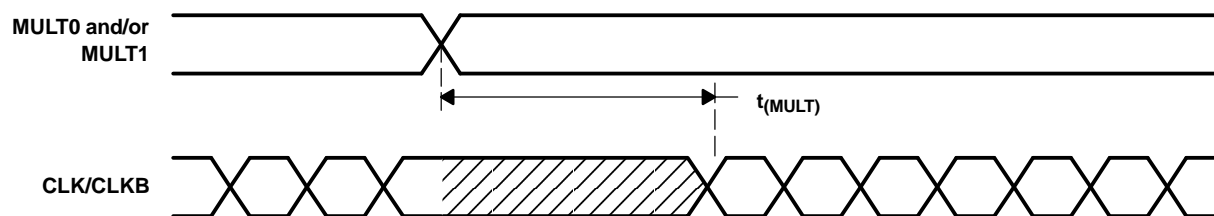
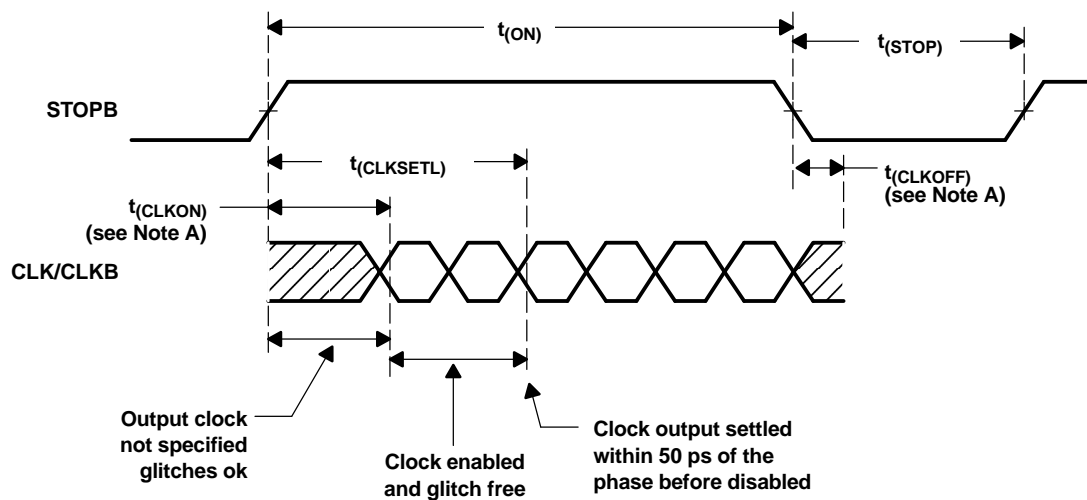


Figure 9. MULT Transition Timings

**PARAMETER MEASUREMENT INFORMATION (continued)**

A.  $V_{ref} = V_O \pm 200 \text{ mV}$

**Figure 10. STOPB Transition Timings**

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">CDCFR83ADBQ</a>	Active	Production	SSOP (DBQ)   24	50   TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCFR83A
CDCFR83ADBQG4	Active	Production	SSOP (DBQ)   24	50   TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCFR83A
<a href="#">CDCFR83ADBQR</a>	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCFR83A

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCFR83ADBQR	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCFR83ADBQR	SSOP	DBQ	24	2500	353.0	353.0	32.0

DBQ (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AE.

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